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(54) Title: SOFT POLISHING PAD FOR POLISHING A SEMICONDUCTOR SUBSTRATE

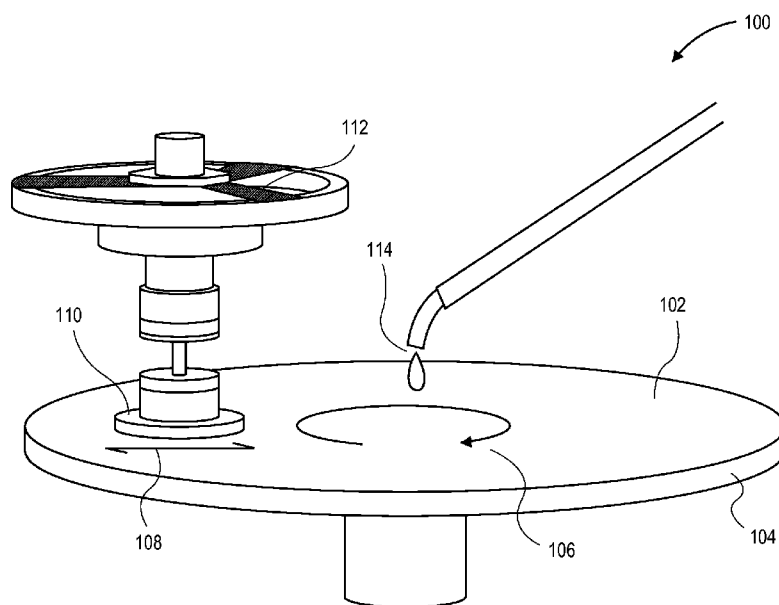


FIG. 1

(57) Abstract: Soft polishing pads for polishing semiconductor substrates are described. A soft polishing pad includes a molded homogeneous polishing body having a thermoset, closed cell polyurethane material with a hardness approximately in the range of 20 Shore D to 45 Shore D.



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